

Film Capacitors

EMI Suppression Capacitors (MKP)

Series/Type: B32923E/F ... B32928E/F

Date: May 2009

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B32926E3335M000	B32926C3335*	2012-12-21	2013-03-31	2013-06-30
B32926E3225M000	B32926C3225*	2012-12-21	2013-03-31	2013-06-30
B32926E3225K000	B32926C3225*	2012-12-21	2013-03-31	2013-06-30

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Ordering Code	Substitute Product	Date of Withdrawal	Deadline Last Orders	Last Shipments
B32926E3206M000	B32928C3206	2012-12-21	2013-03-31	2013-06-30
B32926E3156M000	B32926C3156M,B3 2926D3156	2012-12-21	2013-03-31	2013-06-30
B32926E3156K000	B32926C3156M,B3 2926D3156	2012-12-21	2013-03-31	2013-06-30
B32926E3106M000	B32926C3106*	2012-12-21	2013-03-31	2013-06-30
B32926E3106K000	B32926C3106*	2012-12-21	2013-03-31	2013-06-30
B32924F3335K000	B32924D3335K*	2012-12-21	2013-03-31	2013-06-30
B32924F3225K189	B32924C3225*	2012-12-21	2013-03-31	2013-06-30
B32924F3225K000	B32924C3225*	2012-12-21	2013-03-31	2013-06-30
B32924E3685M000	B32926C3685*	2012-12-21	2013-03-31	2013-06-30
B32924E3475M000	B32924C3475M*	2012-12-21	2013-03-31	2013-06-30
B32924E3565M000	B32924C3565*	2012-12-21	2013-03-31	2013-06-30
B32924E3335M189	B32924C3335M*	2012-12-21	2013-03-31	2013-06-30
B32924E3335M000	B32924C3335M*	2012-12-21	2013-03-31	2013-06-30
B32924E3825M000	B32926C3825*	2012-12-21	2013-03-31	2013-06-30
B32924E3225M189	B32924C3225*	2012-12-21	2013-03-31	2013-06-30
B32924E3225M000	B32924C3225*	2012-12-21	2013-03-31	2013-06-30
B32923E3335M000	B32924C3335M*,B3 2924D3335K*	2012-12-21	2013-03-31	2013-06-30
B32923E3335K000	B32924C3335M*,B3 2924D3335K*	2012-12-21	2013-03-31	2013-06-30
B32924F3685K000	B32926C3685*	2012-12-21	2013-03-31	2013-06-30
B32924F3475K000	B32924D3475K*	2012-12-21	2013-03-31	2013-06-30
B32923E3225M000	B32923C3225*	2012-12-21	2013-03-31	2013-06-30
B32924F3565K000	B32924C3565*	2012-12-21	2013-03-31	2013-06-30
B32928E3456M000		2012-12-21	2013-03-31	2013-06-30
B32928E3406M000		2012-12-21	2013-03-31	2013-06-30
B32928E3406K000		2012-12-21	2013-03-31	2013-06-30
B32928E3306M000	B32928C3306M*	2012-12-21	2013-03-31	2013-06-30
B32928E3306K000	B32928C3306M*	2012-12-21	2013-03-31	2013-06-30
B32928E3256M000	B32928C3256	2012-12-21	2013-03-31	2013-06-30
B32928E3256K000	B32928C3256	2012-12-21	2013-03-31	2013-06-30
B32926F3206K000	B32928C3206	2012-12-21	2013-03-31	2013-06-30
B32926E3685M000	B32926C3685*	2012-12-21	2013-03-31	2013-06-30
B32926E3685K000	B32926C3685*	2012-12-21	2013-03-31	2013-06-30
B32926E3475M000	B32926C3475*	2012-12-21	2013-03-31	2013-06-30

For further information please contact your nearest EPCOS sales office, which will also support you in selecting a suitable substitute. The addresses of our worldwide sales network are presented at www.epcos.com/sales.

EMI suppression capacitors (MKP)

Efficient filtering - X2 / 305 V AC

Typical applications

- X2 class for interference suppression
- "Across the line" applications

Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1): 40/110/56

Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Capacitance value up to 45 µF
- Very small dimensions
- Good self-healing properties
- High voltage capability

Terminals

- Parallel wire leads, lead-free tinned
- Standard lead lengths: 6 -1 mm
- Special lead lengths available on request

Marking

Manufacturer's logo, lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated AC voltage (IEC), series number, sub-class (X2), dielectric code (MKP), climatic category, passive flammability category, approvals.

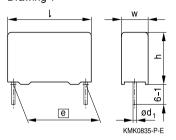
Delivery mode

Bulk (untaped) Reel

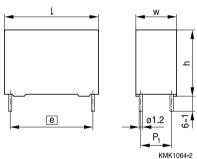
For taping details, refer to chapter "Taping and packing"

Dimensional drawings

Drawing 1



Drawing 2



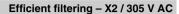
Dimensions in mm

Lead spacing Lead		Туре	Drawing
<i>e</i> ±0.4	diameter		
	d ₁		
22.5	0.8	B32923E	1
27.5	0.8	B32924E/F	1
37.5	1.0	B32926E/F	1
52.5	1.2	B32928E	2

Marking example









Approvals

Approval marks	Standards	Certificate
3 410	IEC 60384-14	40021331
7.1	UL 1283	E301966
c FAL 1)	CSA C22.2 No.8	E301966

¹⁾ approved by UL

Overview of available types

Lead spacing	22.5 mm	27.5 mm	37.5 mm	52.5 mm
Туре	B32923E	B32924E/F	B32926E/F	B32928E
C _R (μF)				
2.2				
3.3				
4.7				
5.6				
6.8				
8.2				
10				
15				
20				
25				
30				
40				
45				





Efficient filtering - X2 / 305 V AC

Ordering codes and packing units

Lead spacing	C _R	Max. dimensions	Ordering code	Reel	Untaped
		$w \times h \times l$	(composition see		
mm	μF	mm	below)	pcs./MOQ	pcs./MOQ
22.5	2.2	$12.0 \times 22.0 \times 26.5$	B32923E3225M*** ◆	_	1800
	3.3	$14.5\times29.5\times26.5$	B32923E3335+***	_	1040
27.5	2.2	$11.0 \times 21.0 \times 31.5$	B32924E3225M***	1400	2352
	2.2	$12.5 \times 21.5 \times 31.5$	B32924F3225K***	1200	2100
	3.3	$14.0\times24.5\times31.5$	B32924E3335M*** ◆	1000	1848
	3.3	$15.0\times24.0\times31.5$	B32924F3335K***	_	1680
	4.7	$16.0 \times 32.0 \times 31.5$	B32924F3475K***	_	1064
	4.7	$18.0 \times 27.5 \times 31.5$	B32924E3475M*** ◆	_	1428
	5.6	$18.0 \times 33.0 \times 31.5$	B32924F3565K***	_	952
	5.6	$19.0 \times 30.0 \times 31.5$	B32924E3565M***	_	896
	6.8	$21.0 \times 31.0 \times 31.5$	B32924E3685M*** ◆	_	784
	6.8	$22.0 \times 36.5 \times 31.5$	B32924F3685K***	_	784
	8.2	$22.0 \times 36.5 \times 31.5$	B32924E3825M*** ◆	_	784
37.5	2.2	$12.0 \times 22.0 \times 42.0$	B32926E3225+***	_	1620
	3.3	$12.0 \times 22.0 \times 42.0$	B32926E3335M***	_	1620
	4.7	$14.0 \times 25.0 \times 42.0$	B32926E3475M***	_	1380
	6.8	$18.0 \times 32.5 \times 42.0$	B32926E3685+***	_	720
	10	$20.0 \times 39.5 \times 42.0$	B32926E3106+*** ◆	_	640
	15	$28.0 \times 37.0 \times 42.0$	B32926E3156+*** ◆	_	440
	20	$28.0 \times 42.5 \times 42.0$	B32926E3206M*** ◆	_	440
	20	$30.0 \times 45.0 \times 42.0$	B32926F3206K***	_	200
52.5	25	$30.0 \times 45.0 \times 57.5$	B32928E3256+*** ◆	_	280
	30	$30.0\times45.0\times57.5$	B32928E3306+*** ◆	_	280
	40	$35.0 \times 50.0 \times 57.5$	B32928E3406+*** ◆	_	108
	45	$35.0 \times 50.0 \times 57.5$	B32928E3456M*** ◆	_	108

◆ Preferred type

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

Composition of ordering code

+= Capacitance tolerance code: *** = Packaging code: $M = \pm 20\%$ 189 = Reel

 $K = \pm 10\%$ 000 = Untaped (lead length 6 -1 mm)



Efficient filtering - X2 / 305 V AC



Technical data

Maximum continuous DC voltage V _{DC}	500 V
Maximum continuous AC voltage V _{AC}	310 V (50/60 Hz)
Rated AC voltage (IEC 60384-14)	305 V (50/60 Hz)
Max. operating temperature $T_{\text{op,max}}$	+110 °C
DC test voltage	2121 V, 2 s
Dissipation factor tan δ (in 10 ⁻³)	at 1 kHz: 2
at 20 °C (upper limit values)	
Insulation resistance R _{ins}	30 000 s
or time constant $\tau = C_R \cdot R_{ins}$	
at 100 V DC, 20 °C,	
rel. humidity ≤ 65% and for 60 s	
(minimum as-delivered values)	
Passive flammability category	В
to IEC 40 (CO) 752	
Capacitance tolerances	±10% (K), ±20% (M)
(measured at 1 kHz)	

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/us.

" k_0 " represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in $V^2/\mu s$.

Note:

The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt and ko values

Lead spacing	22.5 mm	27.5 mm	37.5 mm	52.5 mm
dV/dt in V/μs	140	100	70	40
k ₀ in V²/μs	120 400	86 000	60 200	34 400

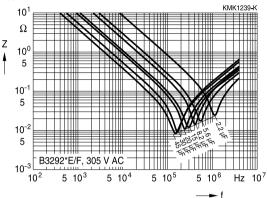




Efficient filtering - X2 / 305 V AC

Impedance Z versus frequency f

(typical values)





Efficient filtering - X2 / 305 V AC



Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

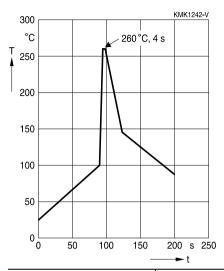
1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series	S	Solder bath temperature	Soldering time
MKT	boxed (except 2.5 \times 6.5 \times 7.2 mm)	260 ±5 °C	10 ±1 s
	coated		
	uncoated (lead spacing > 10 mm)		
MFP			
MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤ 7.5 mm)		< 4 s
MKT	uncoated (lead spacing ≤ 10 mm)		recommended soldering
	insulated (B32559)		profile for MKT uncoated
			(lead spacing ≤ 10 mm) and
			insulated (B32559)







Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane	
Shield	Heat-absorbing board, (1.5 $\pm 0.5)$ mm thick, between capacitor body and liquid solder	
Evaluation criteria:		
Visual inspection	No visible damage	
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors	
$tan \ \delta$	As specified in sectional specification	



Efficient filtering - X2 / 305 V AC



1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
 diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
 - MKP/MFP 110 °C
 - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering





Efficient filtering - X2 / 305 V AC

2 Cleaning

To determine whether the following solvents, often used to remove flux residues and other substances, are suitable for the capacitors described, refer to the table below:

Туре	Ethanol, isopropanol, n-propanol	n-propanol-water mixtures, water with surface tension-reducing tensides (neutral)	Solvent from table A (see next page)	Solvent from table B (see next page)
MKT (uncoated)	Suitable	Unsuitable	In part suitable	Unsuitable
MKT, MKP, MFP (coated/boxed)		Suitable	Suitable	

Even when suitable solvents are used, a reversible change of the electrical characteristics may occur in uncoated capacitors immediately after they are washed. Thus it is always recommended to dry the components (e.g. 4 h at 70 °C) before they are subjected to subsequent electrical testing.

Table AManufacturers' designations for trifluoro-trichloro-ethane-based cleaning solvents (selection)

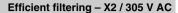
Trifluoro-trichloro- ethane	Mixtures of trifluoro-trichloro-ethane with ethanol and isopropanol	Manufacturer
Freon TF	Freon TE 35; Freon TP 35; Freon TES	Du Pont
Frigen 113 TR	Frigen 113 TR-E; Frigen 113 TR-P; Frigen TR-E 35	Hoechst
Arklone P	Arklone A; Arklone L; Arklone K	ICI
Kaltron 113 MDR	Kaltron 113 MDA; Kaltron 113 MDI; Kaltron 113 MDI 35	Kali-Chemie
Flugene 113	Flugene 113 E; Flugene 113 IPA	Rhone-Progil

Table B (worldwide banned substances)

Manufacturers' designations for unsuitable cleaning solvents (selection)

Mixtures of chlorinated hydrocarbons and ketones with fluorated hydrocarbons	Manufacturer
Freon TMC; Freon TA; Freon TC	Du Pont
Arklone E	ICI
Kaltron 113 MDD; Kaltron 113 MDK	Kali-Chemie
Flugene 113 CM	Rhone-Progil







3 Embedding of capacitors in finished assemblies

In many applications, finished circuit assemblies are embedded in plastic resins. In this case, both chemical and thermal influences of the embedding ("potting") and curing processes must be taken into account.

Our experience has shown that the following potting materials can be recommended: non-flexible epoxy resins with acid-anhydride hardeners; chemically inert, non-conducting fillers; maximum curing temperature of 100 $^{\circ}$ C.

Caution:

Consult us first if you wish to embed uncoated types!





Efficient filtering - X2 / 305 V AC

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"





Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"





Efficient filtering - X2 / 305 V AC

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_{C}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
β_{C}	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
Δ C/C	Relative capacitance change (relative	Relative Kapazitätsänderung (relative
	deviation of actual value)	Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation	Kapazitätstoleranz (relative Abweichung
	from rated capacitance)	vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change	Absolute Temperaturänderung
	(self-heating)	(Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
Ε	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte
	AC voltage due to thermal limits	Reduzierung der zulässigen Wechselspannung
f_2	Frequency limit for reducing permissible	Grenzfrequenz für strombedingte
_	AC voltage due to current limit	Reduzierung der zulässigen
		Wechselspannung
f_r	Resonant frequency	Resonanzfrequenz
F_D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)





Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
i_z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
L_s	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_0	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R_{i}	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_s	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
$tan \ \delta$	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation	Dielektrischer Anteil des Verlustfaktors
	factor	
$tan \; \delta_{\scriptscriptstyle P}$	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
$tan \; \delta_s$	Series component of dissipation factor	Serienanteil des Verlustfaktors
T_A	Ambient temperature	Umgebungstemperatur
T_{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t_{OL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
T_{op}	Operating temperature	Beriebstemperatur
T _R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t_{SL}	Reference service life	Referenz-Lebensdauer
V_{AC}	AC voltage	Wechselspannung





Symbol	English	German
V _C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_{i}	Input voltage	Eingangsspannung
V_{\circ}	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
ν̂ _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
e	Lead spacing	Rastermaß



Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
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